

WHAT IS CLAIMED IS:

1. An electronic component comprising a contact having a terminal section for brazing and a contact section, said contact comprising:

5 a base member having a surface which is poorly wettable to a weld brazing material;

a finish plating layer formed on the surface of said base member, said finish plating layer being made of a material which is highly wettable to the weld brazing material; and

10 an exposed region of the poorly wettable surface of said base member defined by selectively removing a corresponding region of said highly wettable finish plating layer at said terminal section, said exposed region of the poorly wettable surface of said base member serving as an arresting region for arresting creeping-up of said weld brazing material.

15 2. The electronic component according to claim 1, wherein

a primer plating layer made of a material which is poorly wettable to said weld brazing material is formed on said base member to form the poorly wettable surface thereof,

20 said finish plating layer is formed on said primer plating layer, and
said arresting region is formed by removing a portion of the finish plating layer to thereby expose said primer plating layer.

3. The electronic component according to claim 2, wherein

25 said base member is made of a conductor, and
said primer plating layer formed on the base member is a nickel alloy plating layer.

4. The electronic component according to claim 2, wherein
said base member is made of a non-conductor, and
said primer plating layer formed on the base member of said contact is a nickel
5 alloy plating layer formed by electro-less plating technique.

5. The electronic component according to claim 1, wherein
said base member is made of a material which is poorly wettable to said weld
brazing material and
10 said finish plating layer is formed on said base member, and
said arresting region is formed by removing a portion of said finish plating layer
to thereby expose said base member.

6. The electronic component according to claim 1, wherein
15 said base member is made of a material which is poorly wettable to said weld
brazing material, and
a primer plating layer is formed on said base member,
said finish plating layer is formed on said primer plating layer, and
said arresting region is formed by removing both a portion of the primer plating
20 layer and a portion of the finish plating layer to thereby expose said base member.

7. The electronic component according to any one of claims 3 to 6, wherein said
finish plating layer is any one of gold plating layer, tin or tin alloy plating layer, and lead or
lead alloy plating layer.

8. The electronic component according to claim 6, wherein said primer plating layer
is a nickel alloy plating layer.

9. A method of manufacturing an electronic component comprising a contact having a terminal section for brazing and a contact section, said method comprising the steps of:

constructing a base member of said contact made of a material which is poorly
5 wettable to a weld brazing material;

forming on said base member a finish plating layer made of a material which is highly wettable to the weld brazing material; and

forming an exposed region of said poorly wettable base member by selectively removing a portion of said highly wettable finish plating layer at said terminal section
10 by means of a mechanical processing technique,

said exposed region of said highly wettable base material serving as an arresting region for arresting creeping-up of said weld brazing material.

10. The method according to claim 9, further including the step of:

15 forming a primer plating layer made of a material which is poorly wettable to said weld brazing material on said base member prior to forming said finish plating layer; and wherein

the step of forming the finish plating layer is carried out to form the finish plating layer on the thus formed primer plating layer, and

20 the step of forming the exposed region is carried out to selectively removing both a portion of said primer plating layer and a portion of said finish plating layer by a mechanical processing technique.

11. The method according to claim 9, wherein

25 said base member is made of copper alloy, and

said finish plating layer is made of any one of gold plating layer, tin or tin alloy plating layer, and lead or lead alloy plating layer.

12. The method according to claim 10, wherein

said base member is made of copper alloy, and

said finish plating layer is made of any one of gold plating layer, tin or tin alloy

5 plating layer, and lead or lead alloy plating layer.

13. The method according to claim 10, wherein said primer plating layer is made of
nickel alloy plating layer.

10 14. The method according to any one of claim 9 to 13, wherein said mechanical
processing technique is any of mechanical cutting or grinding technique, electric discharge
machining technique, electron-beam machining technique and laser beam machining
technique.